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INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: 150.0072 0103	Serial No.: Filed herewith
	Applicant(s): Cobbley et al.	Confirmation No.:
	Filing Date: Herewith	Group:

U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
PM		2,628,178	07/29/50	Burnett, et al.			
		3,142,698	07/28/64	Halpern et al.			
		3,825,580	07/23/74	Kato et al.			
		3,832,334	08/27/74	O'Sullivan et al.			
		3,984,749	10/05/76	Müller			
		3,987,019	10/19/76	Gruber et al.			
		4,021,767	05/03/77	Nonaka et al.			
		4,139,693	02/13/79	Schoenberg			
		4,167,546	09/11/79	Korshak, et al.			
		4,209,358	06/24/80	DiLeo et al.			
		4,295,909	10/20/81	Baccei			
		4,309,526	01/05/82	Baccei			
		4,490,515	12/25/84	Mariotti et al.			
		4,533,422	08/06/85	Litke			
		4,793,887	12/27/88	Card et al.			
		4,815,208	03/28/89	Raschke			
		Re 32,889	03/14/89	Litke			
		4,862,245	08/29/89	Pashby et al.			
		5,001,542	03/19/91	Tsukagoshi et al.			
		5,079,098	01/07/92	Liu			
		5,150,195	09/22/92	Nguyen			
↓		5,175,337	12/29/92	Mikuni et al.			
PM		5,252,855	10/12/93	Ogawa			

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PN	5,286,679	02/15/94	Farnworth et al.				
	5,288,794	02/22/94	Attarwala				
	5,328,944	7/12/94	Attarwala et al.				
	5,386,047	01/31/95	Nakos et al.				
	5,424,343	06/13/95	Attarwala				
	5,536,799	07/16/96	Takahashi et al.				
	5,589,554	12/31/96	Hiraoka				
	5,656,945	08/12/97	Cain				
	5,739,205	04/14/98	Nishino et al.				
	5,834,836	11/10/98	Park et al.				
V	5,861,678	01/19/99	Schrock				
PN	5,945,733	08/31/99	Corbett et al.				

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
		NONE						


OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

PN	Chorbadjiev, K. et al., "The effect of fillers upon the properties of electroconductive cyanoacrylate adhesives," <i>Int. J. Adhesion and Adhesives</i> , 8, 143-146 (July 1988).
PN	Cooke, B. D. et al., "Cyanoacrylates and their acid values," <i>Int. J. Adhesion and Adhesives</i> , 13, 73-76 (April 1993).
PN	Denchev et al. "Thermal behaviour and adhesive properties of some cyanacrylate adhesives with increased heat resistance," <i>J Appl Polym Sci.</i> , 47, 1019-1026 (1993).

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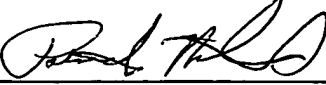
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PM	Drain, K. F., et al., "The effect of moisture on the strength of polycarbonate-cyanoacrylate adhesive bonds," <i>Int. J. Adhesion and Adhesives</i> , 5, 133-136 (July 1985).
	Lee, J., "Synthesis and Ring-Opening Polymerization of 3-Methoxy-4-cyano-2, 9-dioxabicyclo[4.3.0]non-3-ene: Preparation of Alternating Head-to-Head Copolymer of Methyl α -cyanoacrylate and 2, 3-Dihydrofuran," <i>Journal of Polymer Science: Part C: Polymer Letters</i> , 27, 85-91 (1989).
	"LOCTITE®", product description sheet, Rocky Hill, CT, 4 pgs. (December 1996).
	Loctite Corporation, "VARIDOT™ Surface Mount Adhesive Printing Process," advertising brochure, Rocky Hill, CT.
	Ito, H., "Thermal Deesterification and Decarboxylation of Alternating Copolymers of Styrene with β -Substituted <i>t</i> -Butyl α -Cyanoacrylates," <i>Journal of Polymer Science: Part A: Polymer Chemistry</i> , 27, 2871-2881 (1989).
	Melody, D., "Advances in Room Temperature Curing Adhesives and Sealants - A Review," <i>British Polymer Journal</i> , 21, 175-179 (1989).
	Mikuni et al., "Morphological Study of Cyanoacrylate Adhesive Modified by Poly(butadiene-co-acrylonitrile)," <i>Polym. Networks & Blends</i> , 5(3), 159-162 (1995).
	Millet, G., "Properties of Cyanoacrylates - An Overview," <i>Adhesives Age</i> , 27-32 (October 1981).
	Negulescu, I. I. et al., "Thermal Behavior of Poly (α -Cyanoacrylate)," <i>J. Macromol. Sci-Chem.</i> , A24, 75-83 (1987).
	O'Connor, J. T. et al., "Recent Breakthroughs in Thermal Resistant Cyanoacrylate Instant Adhesives," <i>Society of Manufacturing Engineers</i> , 303-22 (1993).
	Okamoto et al. "Bonding Non-Polar Plastics with Alky Cyanoacrylate Instant Adhesive," Annual Technical Conference and Exhibition, Society of Plastics Engineers (1991).
↓	Palmer, B. J. et al., "A New Photoinitiator for Anionic Polymerization," <i>Macromolecules</i> , 28 1328-1329 (1995).
PM	Pepper, D. C., "Kinetics and Mechanisms of Zwitterionic Polymerizations of Alkyl Cyanoacrylates," <i>Polymer Journal</i> , 12, 629-637 (1980).

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PM	Rooney, J. M., "Thermal Degradation of Methyl and Ethyl Cyanoacrylate Oligomers," <i>The British Polymer Journal</i> , 160-163 (December 1981).
	Stein, "Thermal Behavior of Various Poly(2-Cyanoacrylate)S," <i>Journal of Applied Poly Science</i> , 48, 441-447 (1991).
	Tummala et al., eds., <i>Microelectronics Packaging Handbook</i> , Reinhold, New York, NY 554-557 (1989).
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↓ PM	Vijayalakshmi, V. et al., "Synthesis of 3-Substituted-2-cyanoacrylates: Their Evaluation as Cross-linkers in Cyanoacrylate Adhesive Compositions," <i>Journal of Applied Polymer Science</i> , 49, 1387-1394 (1993).

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**SUPPLEMENTAL
INFORMATION
DISCLOSURE
STATEMENT**

SEP 16 2002



Atty. Docket No.: 150.00720103

Serial No.: 09/941,495

Applicant(s): Cobbley et al.

Confirmation No.: 7146

Application Filing Date: 29 August 2001

Group: 2822

Supplemental Information Disclosure
Statement mailed:

September 10 2002

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U.S. PATENT DOCUMENTS

Examiner Initial	Copy Enclosed	Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
PN		4,172,907	10/30/79	Mones et al.			
		4,321,180	03/23/82	Kimura et al.			
		4,720,513	01/19/88	Kameyama et al.			
		5,399,416	03/21/95	Bujard			
		5,841,193	11/24/98	Eichelberger et al.			
		5,893,726	04/13/99	Farnworth et al.			
PN		6,049,125	04/11/00	Brooks et al.			

FOREIGN PATENT DOCUMENTS

Examiner Initial	Copy Enclosed	Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
		None						

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

Examiner Initial	Copy Enclosed	Document Description
PN		Microelectronics Packaging Handbook, 554-557 (1989).

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